

# VPORT 0402 Lead Free Series Specification

Product Name

Series Size EMI & ESD Suppressor VPORT Lead Free Series EIA 0402





# **VPORT 0603 Lead Free Series Engineering Specification**

### 1 Scope

(1)Dual function for EMI and ESD

(2)Compact size EIA 0603

(3)ESD protection for IEC61000-4-2 Level 4

(4) Fixed capacitance suitable for high-speed I/O port transient voltage protection

**RoHS** Compliance

# **Applications**

Applications for I/O Port for Mother Board and Notebook (RS232, USB, PS2, VGA, Audio), Set-Top Box, MP3 Players, DVD Players, and Docking System etc.

## 2 Explanation of Part Number

<u>V</u>	<u>PORT</u>	<u>0603</u>	L	<u>100</u>	<u> </u>	<u>V05</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)

- 1. Series Type: V=Over Voltage Protection
- 2. Series Type: PORT=EMI Protection for I/O Port
- 3. Chip Size (EIA): 0603
- 4. Suffix L= Lead Free
- 5. Capacitance: Value- XXx10<sup>N</sup> $\rightarrow$ XXN Ex: 10pF=10x10<sup>0</sup> $\rightarrow$ 100
- 6. Capacitance Tolerance : K=±10%, M=±20%, No letter: 30%
- 7. Working Voltage

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3 Construction & Dimension





Unit: mm	0603
L	1.60±0.15
W	0.80±0.1
Т	0.80±0.1
С	0.30±0.20

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## 4 Part characteristics:

#### 4.1 Rating(25±5℃)

	Working Voltage	Varistor Voltage	Clamping	Capacitance
Symbol		Voltage	Voltage	Ср
	Volts		Volts	٩٥
Units	(Max.)	Volts	(Max.)	Tolerance
Test Condition	< 10 µ A	1mA DC	1A 8/20 μ s	1MHz
VPORT 0603 L 100 V05		11 – 21	40	10 ± 30%
VPORT 0603 L 330 V05		11 – 21	38	33 ± 30%
VPORT 0603 L 470 V05		9 – 19	37	47 ± 30%
VPORT 0603 L 101 V05	5.5	9 – 19	36	100 ± 30%
VPORT 0603 L 331 V05		8 – 18	32	330 ± 30%
VPORT 0603 L 102 V05		8 – 18	30	1000 ± 30%
VPORT 0603 L 102 KV05		8 – 18	30	1000 ± 10%
VPORT 0603 L 180 KV12		15 – 25	46	18 ± 10%
VPORT 0603 L 220 KV12		15 – 24	42	22 ± 10%
VPORT 0603 L 220 MV12		15 – 24	42	22 ± 20%
VPORT 0603 L 220 V12	12	15 – 25	46	22 ± 30%
VPORT 0603 L 151 V12		15 – 25	44	150 ± 30%
VPORT 0603 L 331 MV12		15 – 17.5	30	330 ± 20%
VPORT 0603 L 331 V12		15 – 25	42	330 ± 30%

- $V_{\text{RMS}}$  Maximum AC operating voltage the varistor can maintain and not exceed10  $\mu\text{A}$  leakage current
- $V_{\text{DC}}$  Maximum DC operating voltage the varistor can maintain and not exceed 10  $\mu\text{A}$  leakage current
- Vc Maximum peak voltage across the varistor measured at 8/20us waveform and 1A pulse current
- Cp Device capacitance measured with zero volt bias 1Vrms at 1MHz.

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# **5** General electrical specifications

#### 5.1 General technical data

Operating temperature	<b>-40 +85</b> ℃
Storage temperature (on board)	-40… +85℃
Response time	<1 ns
Solderability	245±5℃, 3±1sec
Solder leach resistance	260±5℃,10±1sec

# 5.2 Environmental Specifications

Characteristics	Specifications	Test condition
Bias humidity	$\Delta V_V/V_V \leq \pm 10\%$	90%RH, 40°C, Working voltage, 1000 hours
Thermal shock	$\Delta V_V/V_V \leq \pm 10\%$	-40 °C to 85°C, 30 min. Cycle, 5 cycles
Full load voltage	$\Delta V_V/V_V \leq \pm 10\%$	Working voltage, 85 °C, 1000 hours

# 5.3 Storage Condition with package

Storage Time: 12 months max Storage Temperature : 5 to  $40^{\circ}$ C Relative Humidity: to 65 %

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# 6 Taping Package and Label Marking

#### 6.1 Packaging method

Products shall be heat-sealed in the chip pocket, spacing pitch 4-mm of plastic carrier tape with cover tape, and the carrier tape shall be reeled to the reel.

#### 6.2 Carrier tape dimensions



Туре	А	В	С	D	E	F	L	W
0603	8.00±0.30	3.50±0.05	1.75±0.10	2.00±0.05	4.00±0.10	1.50±0.10	1.90±0.15	1.05±0.15

#### 6.3 Taping reel dimensions



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#### 6.4 Taping specifications

There shall be the portion having no product in both the head and the end of taping, and there shall be the cover tape in the head of taping.

#### 6.5 Label Marking

The label specified as follows shall be put on the side of reel.

- (1) Part No.
- (2) Quantity
- (3) Lot No.

Part No. And Quantity shall be marked on outer packaging.

#### 6.6 Quantity of products in the taping package

- (1) Standard quantity : 4000pcs/Reel for VPORT 0603 lead free series
- (2) Shipping quantity is a multiple of standard quantity.

# 7 Precautions for Handling

#### 7.1 Solder cream in reflow soldering

Refer to the recommendable land pattern as printing mask pattern for solder cream.

(1) Print solder in a thickness of 150 to 200  $\mu$ m. Dimensions: millimeters (inches)



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#### 7.2 Precaution for handling of substrate

Do not exceed to bend the board after soldering this product extremely. (Reference examples)

- Mounting place must be as far as possible from the position, which is close to the break line of board, or on the line of large holes of board.
- Do not bend extremely the board, in mounting another components. If necessary, use back-up pin (support pin) to prevent from bending extremely.
- Do not break the board by hand. We recommend to use the machine or the jig to break it.

#### 7.3 Precaution for soldering

Note that rapid heating, rapid cooling or local heating will easily damage this product.

Do not give heat shock over 100°C in the process of soldering. We recommend taking preheating and gradual cooling.

#### 7.4 Recommendable reflow soldering

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate	3° C/second max.
(Tsmax to Tp)	
Preheat	
– Temperature Min (Tsmin)	150 °C
– Temperature Max (Tsmax)	200 °C
– Time (tsmin to tsmax)	60-180 seconds
Time maintained above:	
– Temperature (TL)	217 °C
– Time (tL)	60-150 seconds
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of actual Peak	
Temperature (tp)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

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\*Reference: J-STD-020C

#### 7.5 Caution of flow soldering

We can not recommend the flow soldering to this product, because we afraid that solder bridge happens owing to narrow 0.8mm pitch of this product.

#### 7.6 Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

- (1) The tip temperature must be less than 280°C for the period within 3 seconds by using soldering gun under 30 W.
- (2) The soldering gun tip shall not touch this product directly.

#### 7.7 Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.

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